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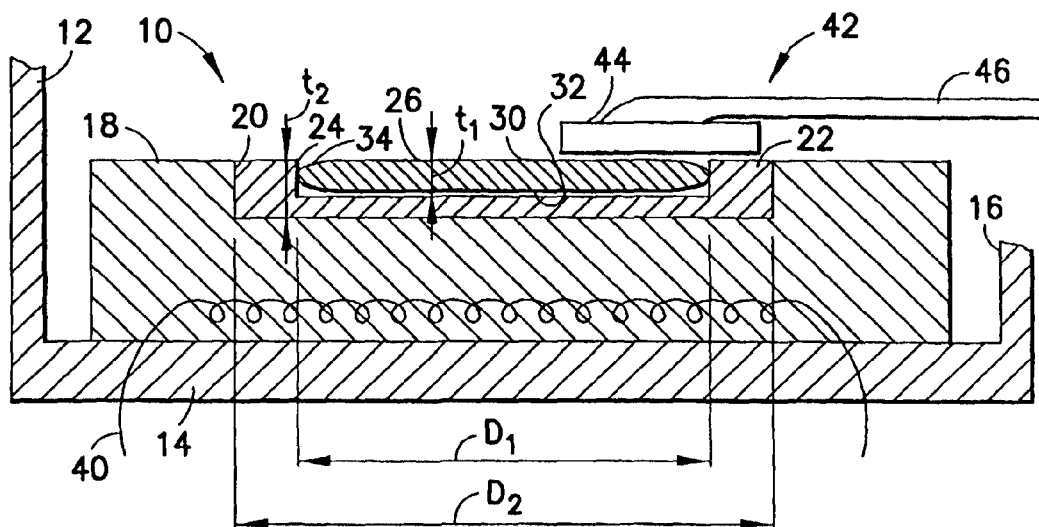
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(54) Title: WATER CARRIER FOR SEMICONDUCTOR PROCESS TOOL



(57) Abstract: A wafer carrier (22) enabling a wafer (26) of different size and/or shape to be processed in a process tool (42) configured for processing a wafer (26) of a predetermined size and/or shape, wherein the wafer carrier (22) has such predetermined size and/or shape and includes at least one recess (20) therein having the different size and/or shape. The wafer carrier (22) enables the use in a process tool (42) (e.g., a semiconductor epitaxial thin film deposition reactor (10) such as a single wafer reactor) of differently sized wafers than those for which the process tool (42) is designed.



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